Express Mail No. **EV 346 809 883US**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Bruno GHYSELEN et al.

Application No: Group Art Unit:

Filing Date: October 14, 2003 Examiner:

Atty. Docket No.: 4717-11400

For: PREVENTIVE TREATMENT METHOD FOR A MULTILAYER SEMICONDUCTOR STRUCTURE

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, enclosed is a PTO form 1449 which lists 5 references for the Examiner's review and consideration. It is respectfully requested that this reference be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee or certification is believed to be due for this submission since this reference is being submitted concurrent with the filing of this application. Should any fees be required, however, please charge such fees to **Winston & Strawn LLP** Deposit Account No. 501-814.

Respectfully submitted,

Date: 10/14/03

Allan A. Fanucci (Reg. No. 30,256)

WINSTON & STRAWN
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Enclosures

LIST OF REFERENCES CITED BY APPLICANT *(Use several sheets if necessary)*	ATTY. DOCKET NO.: 4717-11400	APPLICATION SERIAL NO.:
	APPLICANT: Bruno GHYSELEN et al.	
	FILING DATE:	GROUP:

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AG	FR2823599 English Abstract	10/2002	France			X	
	AH	WO 02084722	10/2002	PCT			X	
	AI							

OTHER REFERENCES *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	AJ	Q-Y. Tong and U. Gosele, "Semiconductor Wafer Bonding Science and Technology" ,Wiley Interscience publication, Johnson Wiley & Sons, Inc.
	AK	O. Rayssac et al , "Application for specific semiconductor processes" SOI to SOIM Technology, Electrochemical Society Proceedings, Vol. 2001-3, pp 39-44 (2001)
	AL	Olivier Rayssac et al., "Influence of Surface Characteristics on Direct Wafer Bonding", LETI/CEA Department de Microtechnologies, Genoble, France
	AM	

EXAMINER	DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with **MPEP 609**; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.